

What is claimed is:

[Claim 1] 1. A package structure comprising:

a lead frame having a plurality of first leads, each of which includes a first recession;

at least a first device; and

a plurality of solder joints respectively positioned in the first recessions for connecting the first device to the lead frame.

[Claim 2] 2. The package structure of claim 1 wherein the first device is a semiconductor chip.

[Claim 3] 3. The package structure of claim 1 wherein the first device is a passive device.

[Claim 4] 4. The package structure of claim 3 wherein the passive device is an electrical resistor, a capacitor, or an inductor.

[Claim 5] 5. The package structure of claim 3 wherein the lead frame comprises a plurality of second leads.

[Claim 6] 6. The package structure of claim 5 wherein the package structure further comprises a plurality of leading wires and at least a second device for connecting the leading wire to the second leads.

[Claim 7] 7. The package structure of claim 3 wherein the lead frame comprises a plurality of second leads, each of which includes a second recession.

[Claim 8] 8. The package structure of claim 7 wherein the package structure comprises at least one second device and a plurality of second solder joints respectively positioned in the second recessions for connecting the second device to the lead frame.

[Claim 9] 9. The package structure of claim 8 wherein the second device is a semiconductor die and the second solder joint is composed of tin or tin alloy.

[Claim 10] 10. The package structure of claim 2 wherein the lead frame comprises a die pad connected to the first device for radiating the heat produced by the first device by serving as a heat sink.

[Claim 11] 11. The package structure of claim 10 wherein the chip sink includes a ground pad connected to both ground and the first device.

[Claim 12] 12. The package structure of claim 1 wherein the first solder joint is composed of tin or tin alloy.